

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): **Kale (et al.)**
Serial No.: **10/784,102**
Filed: **February 20, 2004**

Attorney Docket: **0025-013**
Examiner: **Durnford-Geszvain, Dillon**
Group Art Unit: **2622**

Title: **Integrated Lens And Chip Assembly For A Digital Camera**

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Customer No.: **40972**

INFORMATION DISCLOSURE STATEMENT

Pursuant to 37 C.F.R. §1.56, §1.97, and §1.98, Applicants bring the following documents to the Examiner's attention in the above-referenced application. Forms PTO/SB/08a and PTO/SB/08b listing these documents are submitted herewith. Copies of the references are being provided in accordance with 37 C.F.R. § 1.98(a)(2).

Cited References with Explanation of Relevance:

Applicants bring the following references to the Examiner's attention. The relevance of the cited references is that they are of record in related applications.

1. U.S. Patent No. 7,091,571, issued August 15, 2006, to Park et al.;
2. U.S. Pub. No. 2005/0285016, dated December 29, 2005, to Kong et al.;
3. U.S. Pub. No. 2007/0278394, dated December 6, 2007, to Shangguan et al.;
4. PCT Pub. No. WO 2004/027880, dated April 1, 2004, by Koninklijke Philips Electronics N.V.;
5. EP Patent Doc. EP1429168A2, dated June 16, 2004 by Konica Minolta Holdings, Inc.;
6. JP Patent Doc. JP2002252796, dated September 6, 2002 by Mitsubishi Electric Corp., (English abstract included);
7. JP Patent Doc. JP2003078077, dated March 14, 2003 by Sanyo Electric Co., (English abstract included); and
8. JP Patent Doc. JP2003131112, dated May 8, 2003 by Fujitsu Ltd., (English abstract included).

Cited Patent Applications with Explanation of Relevance:

Applicants also bring the following patent applications and related documents to the Examiner's attention because these patent applications may contain some common subject matter as the above-referenced patent application.

1. PCT Application No. PCT/US2005/005139, filed February 18, 2005, by Flextronics International USA, INC.:

- i. International Search Report and Written Opinion dated June 12, 2007 (cite no. AI); and
- ii. International Preliminary Report on Patentability dated July 19, 2007 (cite no. AJ).

This application is an International Phase Application of US Application No. 10/784,102. Therefore, a copy of the specification and claims of this International Phase Application is not being provided because it would be unnecessarily cumulative.

2. CN Application No. 20058008990.2, filed September 20, 2006, by Flextronics International USA, INC.:

- i. Office Action dated August 1, 2008 (English translation; cite no. AK); and
- ii. Office Action dated June 12, 2009 (English translation; cite no. AL).

This application is a Chinese national-phase application of PCT Application No. PCT/US2005/005139. Therefore, a copy of the specification and claims of this Chinese application is not being provided because it would be unnecessarily cumulative.

3. EP Application No. 05 713 765.5-2202, filed August 15, 2006, by Flextronics International USA, INC.:

- i. Supplementary European Search Report dated December 5, 2008 (cite no. AM); and
- ii. Office Action dated March 17, 2009 (cite no. AN).

This application is a European national-phase application of PCT Application No. PCT/US2005/005139. Therefore, a copy of the specification and claims of this European application is not being provided because it would be unnecessarily cumulative.

4. JP Application No. 2006-554218, filed August 18, 2006, by Flextronics International USA, INC.:

- i. Office Action dated December 3, 2009 (cite no. AO).

This application is a Japanese national-phase application of PCT Application No. PCT/US2005/005139. Therefore, a copy of the specification and claims of this Japanese application is not being provided because it would be unnecessarily cumulative.

5. U.S. Patent Application Serial No. 11/247,993, filed October 11, 2005, by Shangguan et al.:

- i. U.S. Pub. No. 2006/0132644, dated June 22, 2006 by Shangguan et al. (previously cited);
- ii. Office Action dated December 26, 2008 (cite no. AP);
- iii. Office Action dated September 10, 2009 (cite no. AQ); and
- iv. Office Action dated January 6, 2010 (cite no. AR).

6. PCT Application No. PCT/US2006/039521, filed October 10, 2006, by Flextronics AP LLC:

- i. International Search Report and Written Opinion dated August 2, 2007 (cite no. AS); and
- ii. International Preliminary Report on Patentability dated April 24, 2008 (cite no. AT).

This application is an International Phase Application of US Application No. 11/247,993. Therefore, a copy of the specification and claims of this International Phase Application is not being provided because it would be unnecessarily cumulative.

7. CN Application No. 200680046525.2, filed June 11, 2008, by Flextronics AP LLC:

- i. Office Action dated July 10, 2009 (English translation; cite no. AU).

This application is a Chinese national-phase application of PCT Application No. PCT/US2006/039521. Therefore, a copy of the specification and claims of this Chinese application is not being provided because it would be unnecessarily cumulative.

8. EP Application No. 06 816 608.1-1241, filed May 9, 2008, by Flextronics AP LLC:

- i. Extended European Search Report dated March 10, 2010 (cite no. AV).

This application is a European national-phase application of PCT Application No. PCT/US2006/039521. Therefore, a copy of the specification and claims of this European application is not being provided because it would be unnecessarily cumulative.

9. U.S. Patent Application Serial No. 11/444,277, filed May 31, 2006, by Shangguan et al.:

- i. U.S. Pub. No. 2007/0278394, dated December 6, 2007, to Shangguan et al. (cite no. AC);
- ii. Office Action dated August 5, 2008 (cite no. AW);
- iii. Office Action dated May 7, 2009 (cite no. AX); and
- iv. Office Action dated November 18, 2009 (cite no. AY).

10. PCT Application No. PCT/US2007/013014, filed May 31, 2007, by Flextronics AP LLC:

- i. International Search Report and Written Opinion dated August 27, 2008 (cite no. AZ);
and
- ii. International Preliminary Report on Patentability dated December 18, 2009 (cite no. BA).

This application is an International Phase Application of US Application No. 11/444,277. Therefore, a copy of the specification and claims of this International Phase Application is not being provided because it would be unnecessarily cumulative.

11. CN Application No. 200780026542.4, filed January 13, 2009, by Flextronics AP LLC:

- i. CN Application No. 200780026542.4, Office Action dated November 13, 2009 (English translation; cite no. BB).

This application is a Chinese national-phase application of PCT Application No. PCT/US2007/013014. Therefore, a copy of the specification and claims of this Chinese application is not being provided because it would be unnecessarily cumulative.

English abstracts are provided to satisfy the requirement for a concise explanation of the relevance of the non-English references, as provided for in M.P.E.P. §609.04(a)(III).

Citation of the above documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, other than as described above; or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. §1.56(b).

This information disclosure statement is filed before the mailing of a first Office action after the filing of a request for continued examination under §1.114. Therefore, no fee is due. 37 CFR §1.97(b)(4)

Respectfully Submitted,

May 19, 2010
Date: _____

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CERTIFICATE OF ELECTRONIC FILING

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being filed with the United States Patent and Trademark Office on the date shown below via EFS-Web.

May 19, 2010
Date: _____

/Larry E. Henneman, Jr./

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